



Product Change Notification

106295 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 106295 - 00
Change Title: SR870BN4, PCN 106295-00, Product Material, Class 2: New mPGA700 CPU Socket
Date of Publication: May 08, 2006

Key Characteristics of the Change:

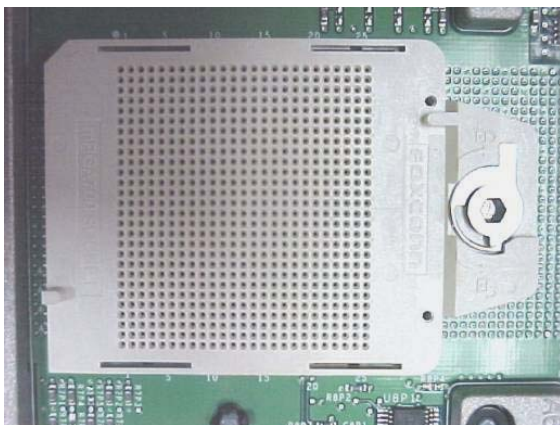
Product Material

Forecasted Key Milestones:

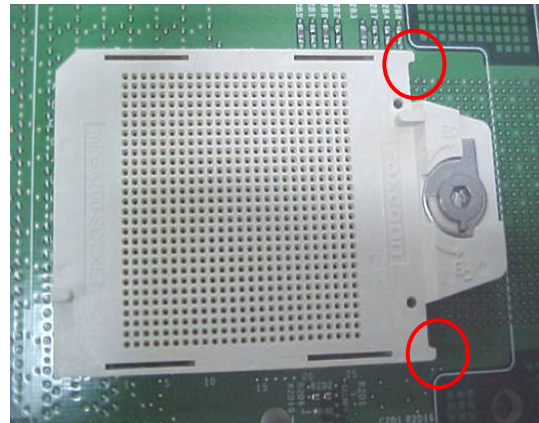
Date Customer Must be Ready to Receive Post-Conversion Material:	May 15, 2006
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Description of Change to the Customer:

The mPGA700 processor socket is being updated to add two shoulder bumps. This will improve pin-shroud alignment, so as to reduce bent pin defect rate. Please refer to following pictures for detail:



Current mPGA Socket



New mPGA Socket: Add two 1mm height bumps (circled RED) on the cover shoulder on both sides

Customer Impact of Change and Recommended Action:

This change has no significant impact on system performance, reliability, quality and functionality.

Products Affected / Intel Ordering Codes:

Affected Product Code	Pre-Change MM#	Post-Change MM#	Pre-Change TA	Post-Change TA
SBNMB000	871267	871267	A96556-019	A96556-019
SBNMB000X	871269	871269	C27422-019	C27422-019

Affected Product Code	Pre-Change MM#	Post-Change MM#	Pre-Change TA or AA	Post-Change TA or AA	Pre-Change PBA	Post-Change PBA
BBACPUBOARD	871298	871298	A97629-322	A97629-322	A55955-322	A55955-322
BBACPUBRDBLK	871304	871304	A55955-350	A55955-350	A55955-322	A55955-322

Reference Documents / Attachments:

Document: _____ **Location #:** _____

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
May 8, 2006	00	Originally Published PCN